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SPECIAL ISSUE ON HUMAN-IN-THE-LOOP SENSING IN COGNITIVE ROBOTIC SYSTEMS

PREFACE



We are pleased to announce our special issue on human-in-the-loop sensing in cognitive robotic systems.



This special issue aims to highlight recent progress in human–robot collaboration, with a particular focus on the new sensors and materials developed for these applications and the related learning and control methods for robot interaction. After a strict review process, we finally selected four articles for the special issue, which are on exoskeletons and control, 3D vision for autonomous driving, collaborative manipulation between a human and a robot arm, and multi-modal sensing and robotic services in COVID-19 hospitals. These articles provide important new knowledge about sensing and control in human–robot collaboration.



We want to thank all authors who submitted their original papers to the special issue. We would also like to thank all reviewers for their valuable and insightful comments that helped improve the quality of each paper. Finally, we give our appreciation to Ms. Sakano of *Sensors and Materials* for her invaluable assistance.

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